



Material Declaration Sheet

Vishay General Semiconductor - VGSC

Date 22/Aug/22

Part / Product Family Details

Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemption used
VSSAF510-M3(HM3) VSSAF512-M3(HM3) VSSAF515-M3(HM3) VSSAF3L45-M3 VSSAF3N50-M3 VSSAF56-M3 VSSAF5L45-M3 VSSAF5N50-M3 VSSA3L45-M3 VSSA5L45-M3 VSSAF3M6-(H)M3 VSSAF3M10-(H)M3 VSSAF5M6-(H)M3 VSSAF5M10-(H)M3 VSSAF5M12-(H)M3 VSSAF5M15-(H)M3 VSSAF5M63-(H)M3 VSSAF3M6-M3 VSSAF3M6HM3 VSSAF3M10-M3 VSSAF3M10HM3 VSSAF522HM3 VSSAF522-M3	YES WITH EXEMPTION	01-12-2004	0.0324	N/A	Yes	China	One

Material Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	DDM		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00150	100.00	1000000	4.63	
Clip	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.00400	100.00	1000000	12.35	
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.01000	100.00	1000000	30.86	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00130	92.50	925000	4.00	Exemption No:7(a)
		Tin	7440-31-5	0.00007	5.00	50000	0.22	
		Silver	7440-22-4	0.00004	2.50	25000	0.11	
Encapsulation	Other duromers	Silica	60676-86-0	0.01208	80.00	800000	37.28	
		Epoxy Resin	29690-82-2	0.00151	10.00	100000	4.66	
		Phenol Resin	9003-35-4	0.00143	9.50	95000	4.43	
		Carbon Black	1333-86-4	0.00008	0.50	5000	0.23	
Surface finish	Other special metals	Tin	7440-31-5	0.00040	100.00	1000000	1.23	

EU-RoHS Directive- MCV of 0.1% by mass (1000 PPM) in homogenous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV 2015/863/EU of 0.01% by mass cadmium ,Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP)

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.
(ii) Substance weight are derived from MSDS.

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into your Design

Vishay General Semiconductor - VGSC
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